



THE BIG DEAL

- Standard small 1008 (2.5mm x 2.0mm) case style
- Low Insertion Loss – Mid band 1.5 dB typical
- Shielded construction preventing filter from de-tuning
- Reduced footprint area by employing LGA (land grid array)
- Surface mountable pick and place standard case style
- Patent pending



Generic photo used for illustration purposes only

CASE STYLE: NL1008C-6

+RoHS Compliant

The +Suffix identifies RoHS Compliance.
See our website for methodologies and qualifications

APPLICATIONS

- Test and Measurement

PRODUCT OVERVIEW

The BFCQ-3402+ LTCC Band Pass Filter achieves a miniature size and high repeatability of performance by utilizing a proprietary LTCC material system and distributed filter topology. The typical passband loss at 29.0 – 39.0 GHz is as low as 1.5 dB, with typical stopband rejections at 21 dB up to 67 GHz. This model handles up to 1W RF input power, and provides a wide operating temperature range from -55 to +125°C. Utilizing a proprietary LTCC material system and a distributed filter topology, this filter is able to achieve repeatable performance on a lot-to-lot basis.

KEY FEATURES

Feature	Advantages
Cost effective	LTCC is scalable technology that is cost effective due to ease of production in high quantities.
Small size (2.5mm x 2.0mm)	Allows for high layout density of circuit boards, while minimizing effects of parasitics.
Surface Mountable	Suitable for very high volume automated assembly process.



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Bandpass Filter

BFCQ-3402+

50Ω 29 to 39 GHz

ELECTRICAL SPECIFICATIONS¹ AT 25°C

Parameter	F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Center Frequency	—	—	—	33.6	—	GHz
Passband	Insertion Loss	F1-F2	—	1.5	2.75	dB
	Return Loss	F1-F2	—	13	—	dB
Stop Band, Lower	Insertion Loss	DC-F3	0.1 – 15	30	40	dB
		15 – 21.9	18	25	—	
Stop Band, Upper	Insertion Loss	F4-F5	44 – 50	14	21	dB
		50 – 67	14	21	—	

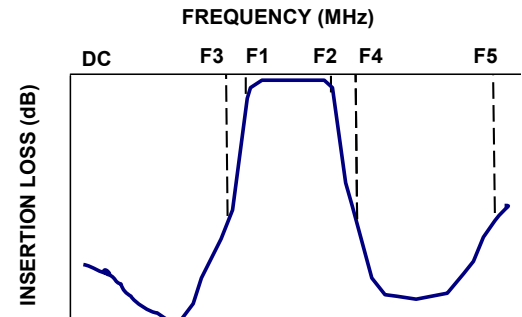
1. Measured on Mini-Circuits Test Board TB-BFCQ-3402C+ with connectors and feedlines de-embedded.

MAXIMUM RATINGS

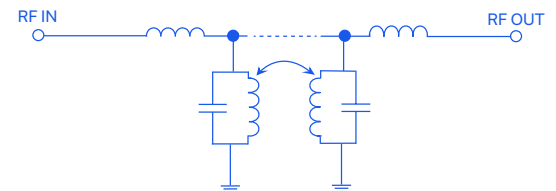
Parameter	Ratings
Operating temperature	-55°C to +125°C
Storage temperature	-55°C to +125°C
RF Power Input	1W

Permanent damage may occur if any of these limits are exceeded.

TYPICAL FREQUENCY RESPONSE



FUNCTIONAL SCHEMATIC





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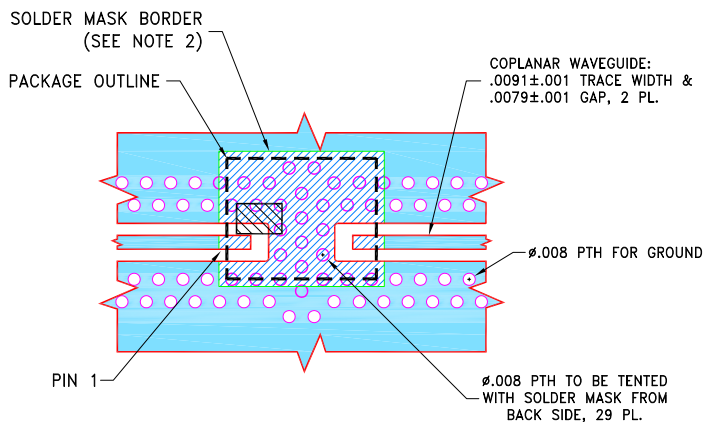
BFCQ-3402+

50Ω 29 to 39 GHz

PAD CONNECTIONS

INPUT	1
OUTPUT	2
GROUND	3

PRODUCT MARKING: UP

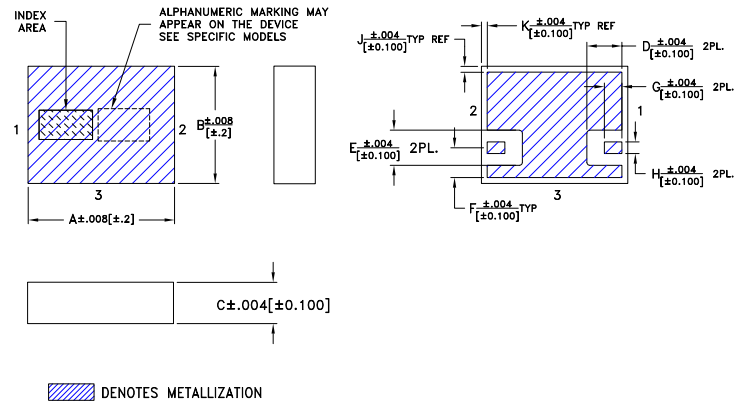
DEMO BOARD MCL P/N: TB-BFCQ-3402C+
SUGGESTED PCB LAYOUT (PL-707)

NOTES:

1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR MEGTRON-7 R5785(N); DIELECTRIC THICKNESS: .0049±.001; CLOTH STYLE: 2116; COPPER: HVLP/HVLP. FOR OTHER MATERIALS LINE WIDTH & GAP MAY NEED TO BE MODIFIED.
2. SOLDER MASK OPENING FOR COMPONENT SOLDERING HAS BEEN INCREASED AGAINST PCB LAND PATTERN RECOMMENDATIONS PER NL1008C-6 AND CAN BE DEVIATED FROM THIS DRAWING TO COMPLY WITH CUSTOMERS' DESIGN RULES.
3. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

-  DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).
-  DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

OUTLINE DRAWING

OUTLINE DIMENSIONS (Inches)
mm

A	B	C	D	E	F	G	H	J	K	wt
.098	.079	.028	.024	.024	.020	.012	.008	.004	.004	grams
2.49	2.01	0.71	0.6	0.6	0.51	0.3	0.2	0.1	0.1	.019

TAPE & REEL INFORMATION: F75



CERAMIC

Bandpass Filter

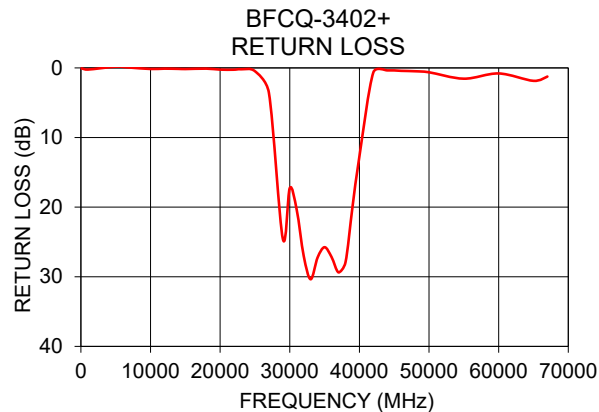
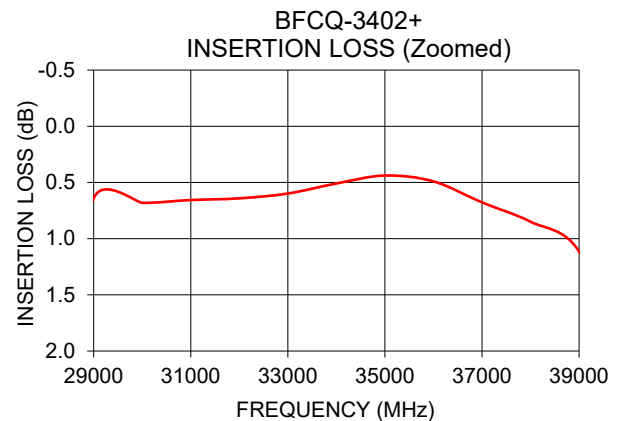
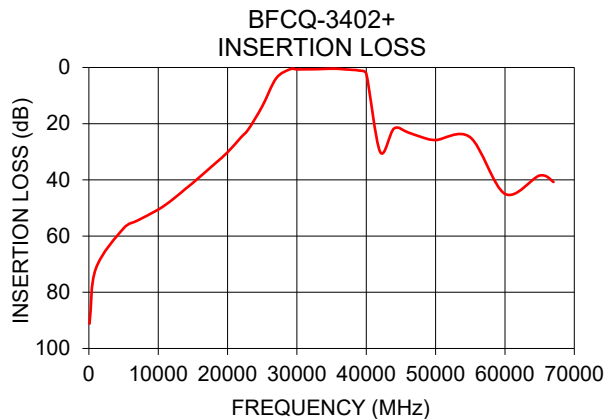
BFCQ-3402+

50Ω

29 to 39 GHz

TYPICAL PERFORMANCE DATA AT 25°C

Frequency (MHz)	Insertion Loss (dB)	Return Loss (dB)
100	91.15	0.07
1000	71.61	0.24
5000	57.25	-0.18
10000	50.57	0.15
15000	41.06	0.16
21900	24.96	0.26
25000	13.82	0.47
29000	0.64	24.55
32000	0.64	27.00
34000	0.51	27.22
39000	1.11	20.03
40000	2.19	12.72
44000	21.72	0.36
48000	24.80	0.48
50000	25.83	0.63
55000	24.86	1.55
60000	44.97	0.80
67000	40.76	1.24

**NOTES**

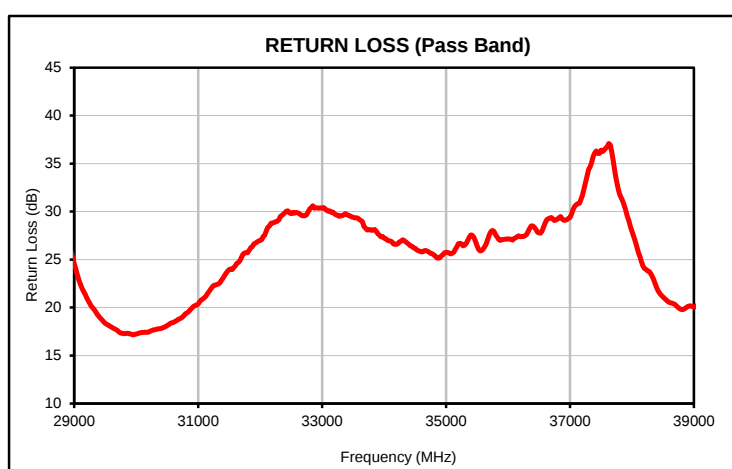
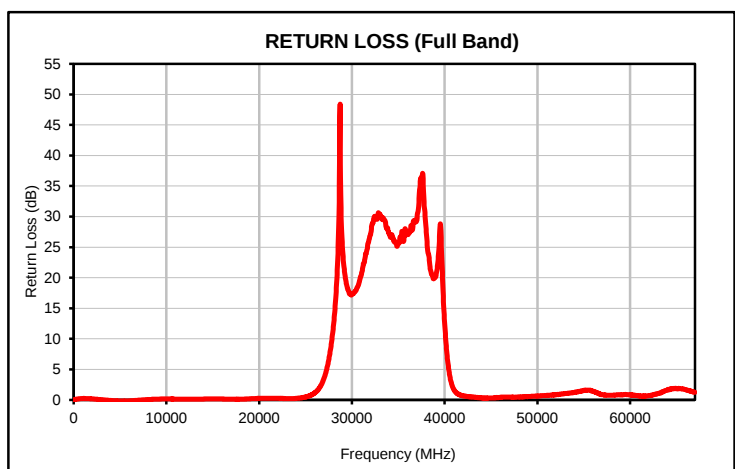
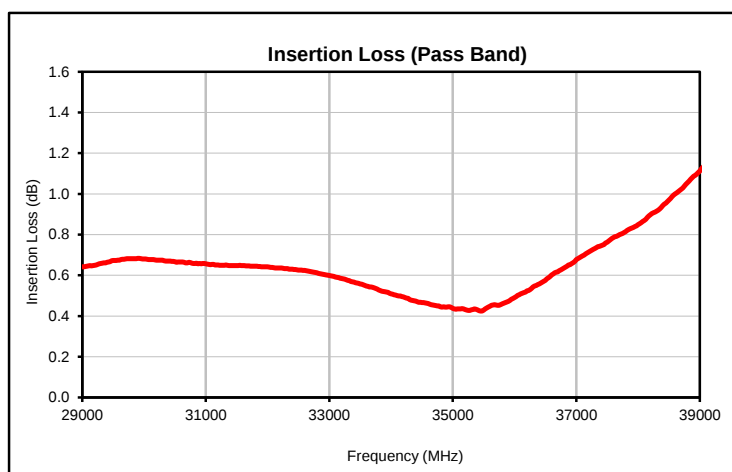
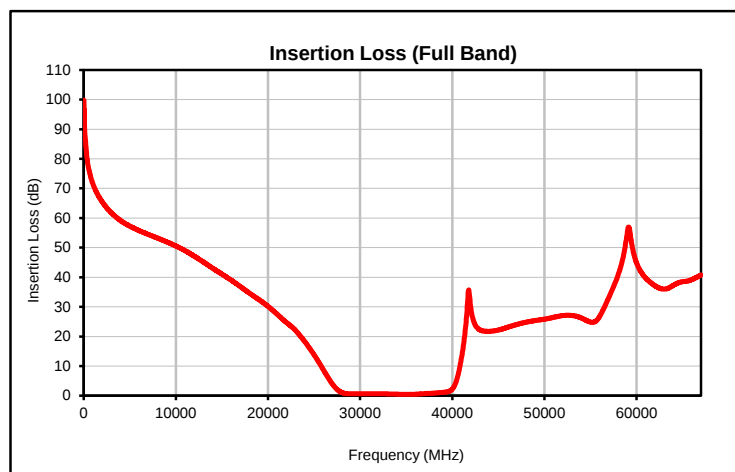
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Typical Performance Data

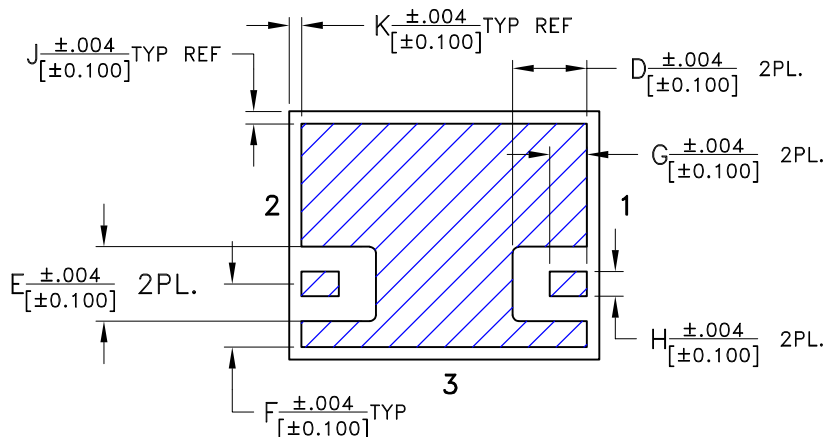
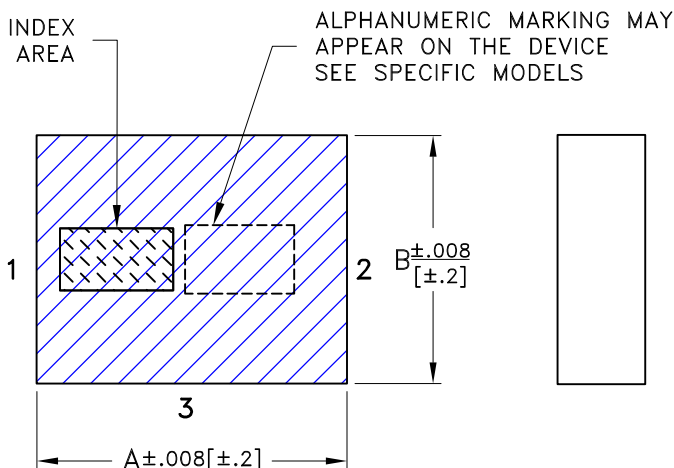
FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
100	91.15	0.07
1000	71.61	0.24
5000	57.25	0.18
7000	54.49	0.05
10000	50.57	0.15
12000	47.13	0.11
14000	43.05	0.14
15000	41.06	0.16
18000	34.61	0.10
20000	30.17	0.25
21900	24.96	0.26
23000	22.01	0.20
25000	13.82	0.47
27000	3.89	3.56
29000	0.64	24.55
30000	0.68	17.25
31000	0.66	20.40
32000	0.64	27.00
33000	0.60	30.36
34000	0.51	27.22
35000	0.44	25.75
36000	0.49	27.16
37000	0.68	29.37
38000	0.85	27.93
39000	1.11	20.03
40000	2.19	12.72
42000	30.02	0.65
44000	21.72	0.36
46000	23.09	0.42
48000	24.80	0.48
50000	25.83	0.63
55000	24.86	1.55
60000	44.97	0.80
65000	38.46	1.86
67000	40.76	1.24

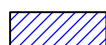
Typical Performance Curves

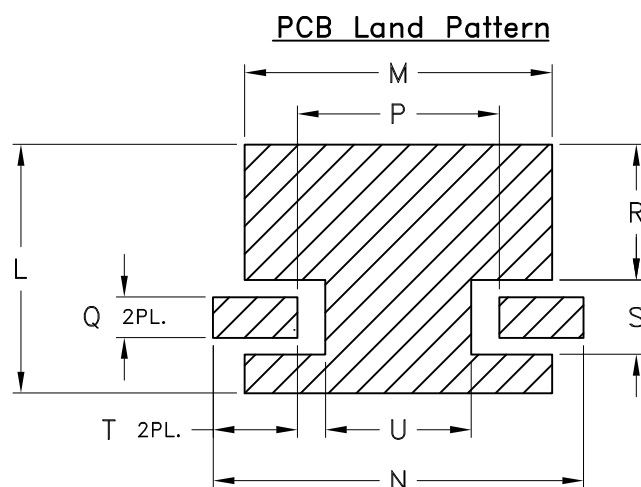


Outline Dimensions

NL1008C-6



 DENOTES METALLIZATION



Suggested Layout,
Tolerance to be within $\pm .002$

CASE#	A	B	C	D	E	F	G	H	J	K	L	M	N
NL1008C-6	.098 (2.50)	.079 (2.00)	.028 (.705)	.024 (.60)	.024 (.60)	.020 (.51)	.012 (.30)	.008 (.20)	.004 (.10)	.004 (.10)	.079 (2.0)	.098 (2.5)	.118 (3.0)

CASE #	P	Q	R	S	T	U	WT, GRAM
NL1008C-6	.064 (1.63)	.013 (.3)	.043 (1.09)	.024 (.60)	.027 (.7)	.046 (1.2)	.019

Dimensions are in inches (mm). Tolerances: 2 Pl. $\pm .01$; 3 Pl. $\pm .005$

Notes:

1. Open style, ceramic base.
2. Termination finish:
For RoHS Case Styles: Tin plate over Nickel plate. All models, (+) suffix.
For RoHS-5 Case Styles: Tin-Lead plate. All models, no (+) suffix.
3. Pad tolerance is non-cumulative. Minimum spacing between each pad is .004.
4. Line width should be designed to match 50 Ω characteristic depending on PCB material and thickness.

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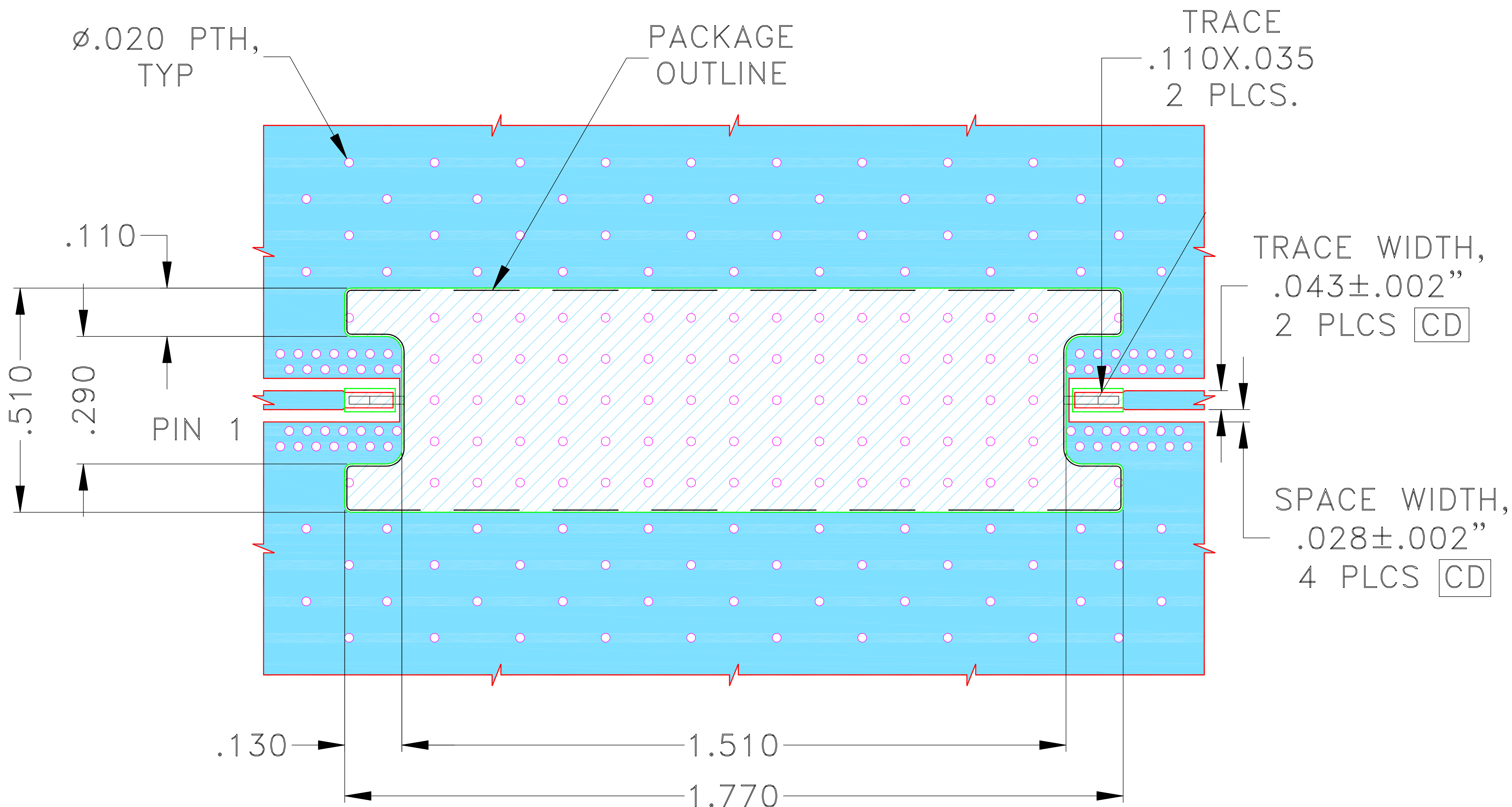
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RF/IF MICROWAVE COMPONENTS

SUGGESTED MOUNTING CONFIGURATION FOR
QN2178-3 CASE STYLE

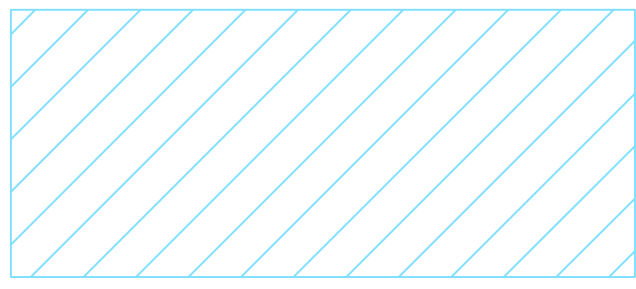


NOTES:

1. TRACE WIDTH IS SHOWN FOR ROGERS(R04350B), WITH DIELECTRIC THICKNESS .020"±.0015". COPPER: 1/2 Oz EACH SIDE.
FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

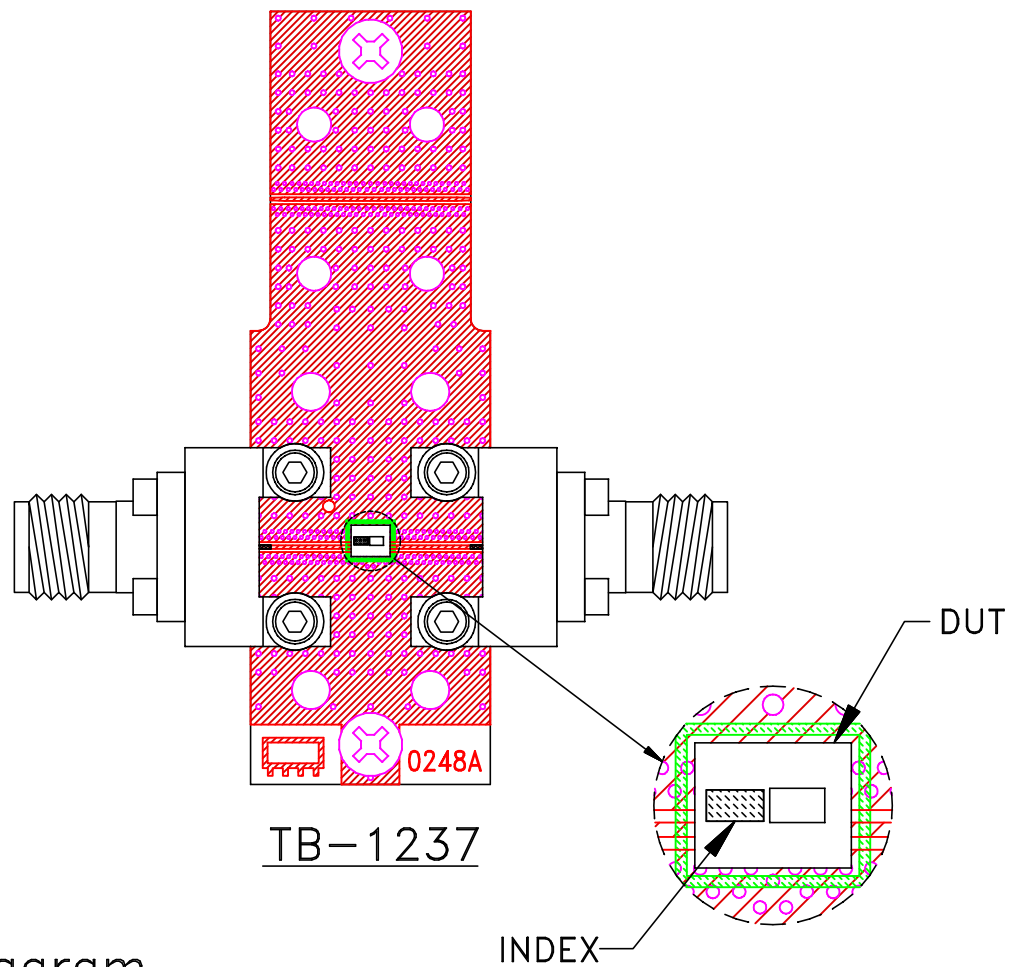


DENOTES PCB COPPER LAYOUT WITH SMOBC
(SOLDER MASK OVER BARE COPPER)

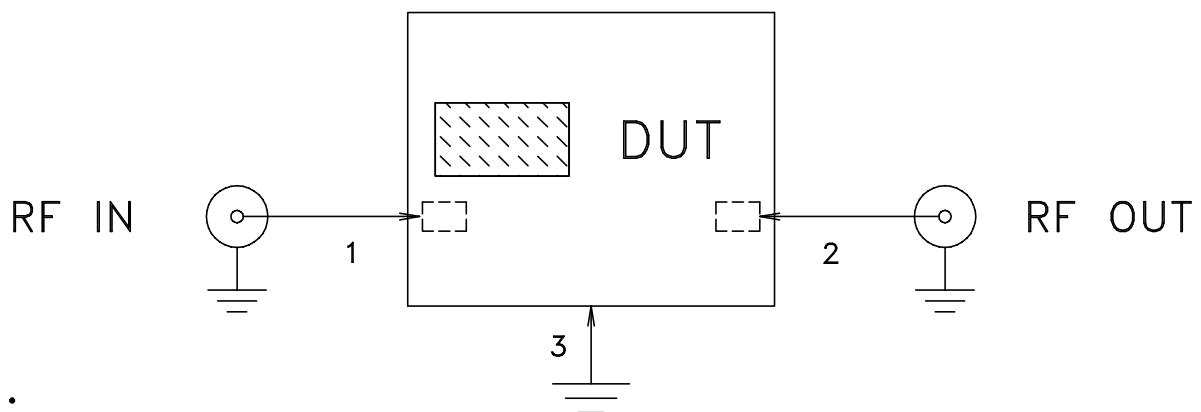


DENOTES COPPER LAND PATTERN FREE OF SOLDERMASK

Evaluation Board and Circuit



Schematic diagram



Notes:

1. 50 Ohm 1.85 Female connectors.
2. PCB Material: Megtron 7(N) or equivalent,
Dielectric Constant=3.4, Thickness=.005 inch.

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All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Thermal Cycling	-55 to 125°C, 100 cycles, Dwell Time 15 minutes.	MIL-STD-202, Method 107, Condition A-3
Mechanical Shock	50g, 11ms half-sine, 18 shocks applied each to 3 axes	MIL-STD-202 Method 213, Condition A
Vibration	10-2000Hz sine, 20g, 12 cycles applied each to 3 axes	MIL-STD-202, Method 204, Condition D
Constant Acceleration	30Kg, Y1 Direction	MIL-STD-883, Method 2001, Condition E
Humidity	85°C, 90-95% Relative Humidity, 250hours	
Solderability	10X / 30X Magnification	J-STD-002C Test S, J-STD-002C Test S1
High Temp Storage	125°C, 250 hours	